



**Panel Session:**  
***Amending Moore's Law for Embedded Applications***

**James C. Anderson**  
**MIT Lincoln Laboratory**

**HPEC04**  
**29 September 2004**

**This work is sponsored by the HPEC-SI (high performance embedded computing software initiative) under Air Force Contract F19628-00-C-0002. Opinions, interpretations, conclusions and recommendations are those of the author and are not necessarily endorsed by the United States Government.**

**Reference to any specific commercial product, trade name, trademark or manufacturer does not constitute or imply endorsement.**

# Report Documentation Page

Form Approved  
OMB No. 0704-0188

Public reporting burden for the collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden, to Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington VA 22202-4302. Respondents should be aware that notwithstanding any other provision of law, no person shall be subject to a penalty for failing to comply with a collection of information if it does not display a currently valid OMB control number.

1. REPORT DATE <b>01 FEB 2005</b>		2. REPORT TYPE <b>N/A</b>		3. DATES COVERED <b>-</b>	
4. TITLE AND SUBTITLE <b>Panel Session:Amending Moores Law for Embedded Applications</b>				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S)				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) <b>MIT Lincoln Laboratory</b>				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT <b>Approved for public release, distribution unlimited</b>					
13. SUPPLEMENTARY NOTES <b>See also ADM001742, HPEC-7 Volume 1, Proceedings of the Eighth Annual High Performance Embedded Computing (HPEC) Workshops, 28-30 September 2004. , The original document contains color images.</b>					
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT	18. NUMBER OF PAGES	19a. NAME OF RESPONSIBLE PERSON
a. REPORT <b>unclassified</b>	b. ABSTRACT <b>unclassified</b>	c. THIS PAGE <b>unclassified</b>			



# Objective, Questions for the Panel & Schedule

- **Objective: identify & characterize factors that affect the impact of Moore's Law on embedded applications**
- **Questions for the panel**
  - 1). Moore's Law: what's causing the slowdown?
  - 2). What is the contribution of Moore's Law to improvements at the embedded system level?
  - 3). Can we preserve historical improvement rates for embedded applications?

**Panel members & audience may hold diverse, evolving opinions**

- **Schedule**
  - – 1540-1600: panel introduction & overview
  - 1600-1620: guest speaker Dr. Robert Schaller
  - 1620-1650: panelist presentations
  - 1650-1720: open forum
  - 1720-1730: conclusions & the way ahead



# Panel Session: *Amending Moore's Law for Embedded Applications*

**Moderator: Dr. James C. Anderson,  
MIT Lincoln Laboratory**



**Dr. Richard Linderman,  
Air Force Research Laboratory**



**Mr. David Martinez,  
MIT Lincoln Laboratory**

**Dr. Mark Richards,  
Georgia Institute of Technology**

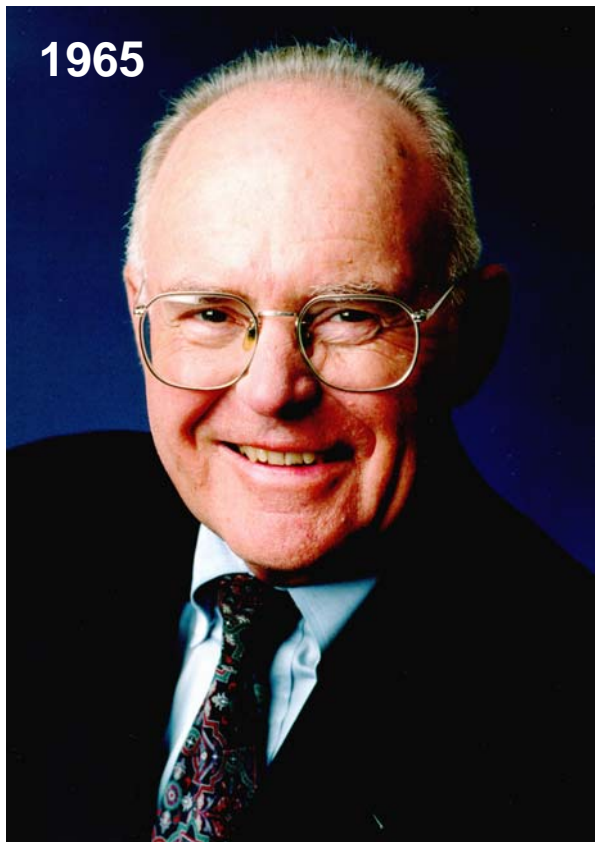


**Dr. Robert R. Schaller,  
College of Southern Maryland**





# Four Decades of Progress at the System Level



**Gordon Moore publishes  
“Cramming more components  
onto integrated circuits”**

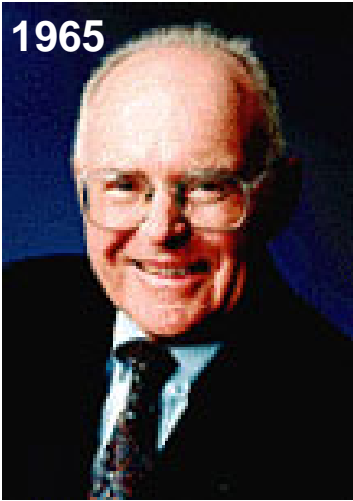


**Computers lose badly at chess**



# Four Decades of Progress at the System Level

1965



Gordon Moore publishes "Cramming more components onto integrated circuits"

1997



Robert Schaller publishes "Moore's Law: past, present and future"



*Deep Blue* (1270kg) beats chess champ Kasparov

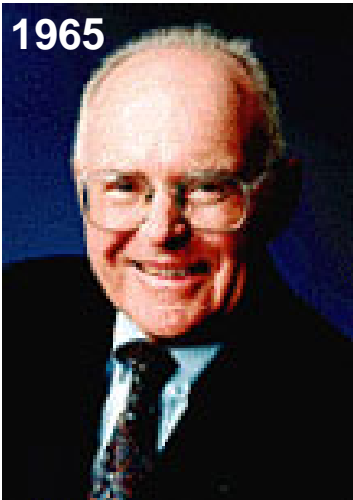
Computers lose badly at chess





# Four Decades of Progress at the System Level

1965



Gordon Moore publishes "Cramming more components onto integrated circuits"

1997



Robert Schaller publishes "Moore's Law: past, present and future"

2002-2004



Mark Richards (with Gary Shaw) publishes "Sustaining the exponential growth of embedded digital signal processing capability"



Chess champ Kramnik ties Deep Fritz & Kasparov ties Deep Junior (10K lines C++ running on 15 GIPS server using 3 Gbytes)



Computers lose badly at chess

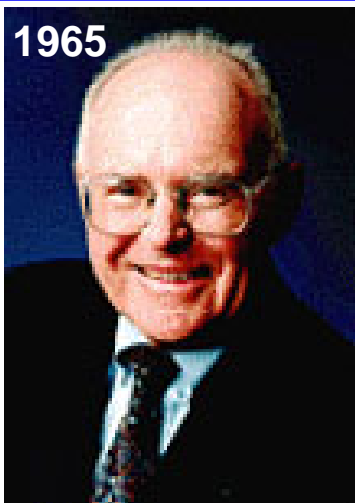


Deep Blue (1270kg) beats chess champ Kasparov



# Four Decades of Progress at the System Level

1965



Gordon Moore publishes "Cramming more components onto integrated circuits"

1997



Robert Schaller publishes "Moore's Law: past, present and future"

2002-2004

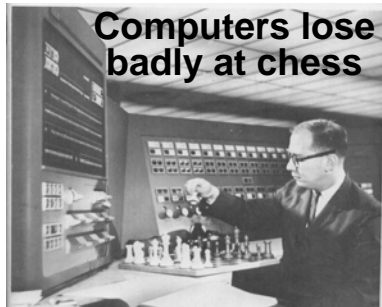


Mark Richards (with Gary Shaw) publishes "Sustaining the exponential growth of embedded digital signal processing capability"

~2005



Deep Dew hand-held chess champ (0.6L & 0.6kg) uses 22 AA cells (Li/FeS<sub>2</sub>, 22W for 3.5 hrs) & COTS parts incl. voice I/O chip



Computers lose badly at chess



Deep Blue (1270kg) beats chess champ Kasparov



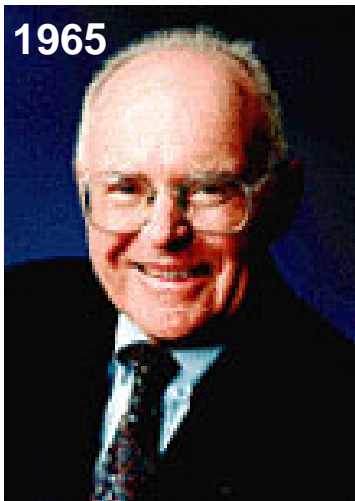
Chess champ Kramnik ties Deep Fritz & Kasparov ties Deep Junior (10K lines C++ running on 15 GIPS server using 3 Gbytes)





# Four Decades of Progress at the System Level

1965



Gordon Moore publishes "Cramming more components onto integrated circuits"

1997



Robert Schaller publishes "Moore's Law: past, present and future"

2002-2004



Mark Richards (with Gary Shaw) publishes "Sustaining the exponential growth of embedded digital signal processing capability"

~2005



Deep Dew hand-held chess champ (0.6L & 0.6kg) uses 22 AA cells (Li/FeS<sub>2</sub>, 22W for 3.5 hrs) & COTS parts incl. voice I/O chip

Computers lose badly at chess



Deep Blue (1270kg) beats chess champ Kasparov



Chess champ Kramnik ties Deep Fritz & Kasparov ties Deep Junior (10K lines C++ running on 15 GIPS server using 3 Gbytes)

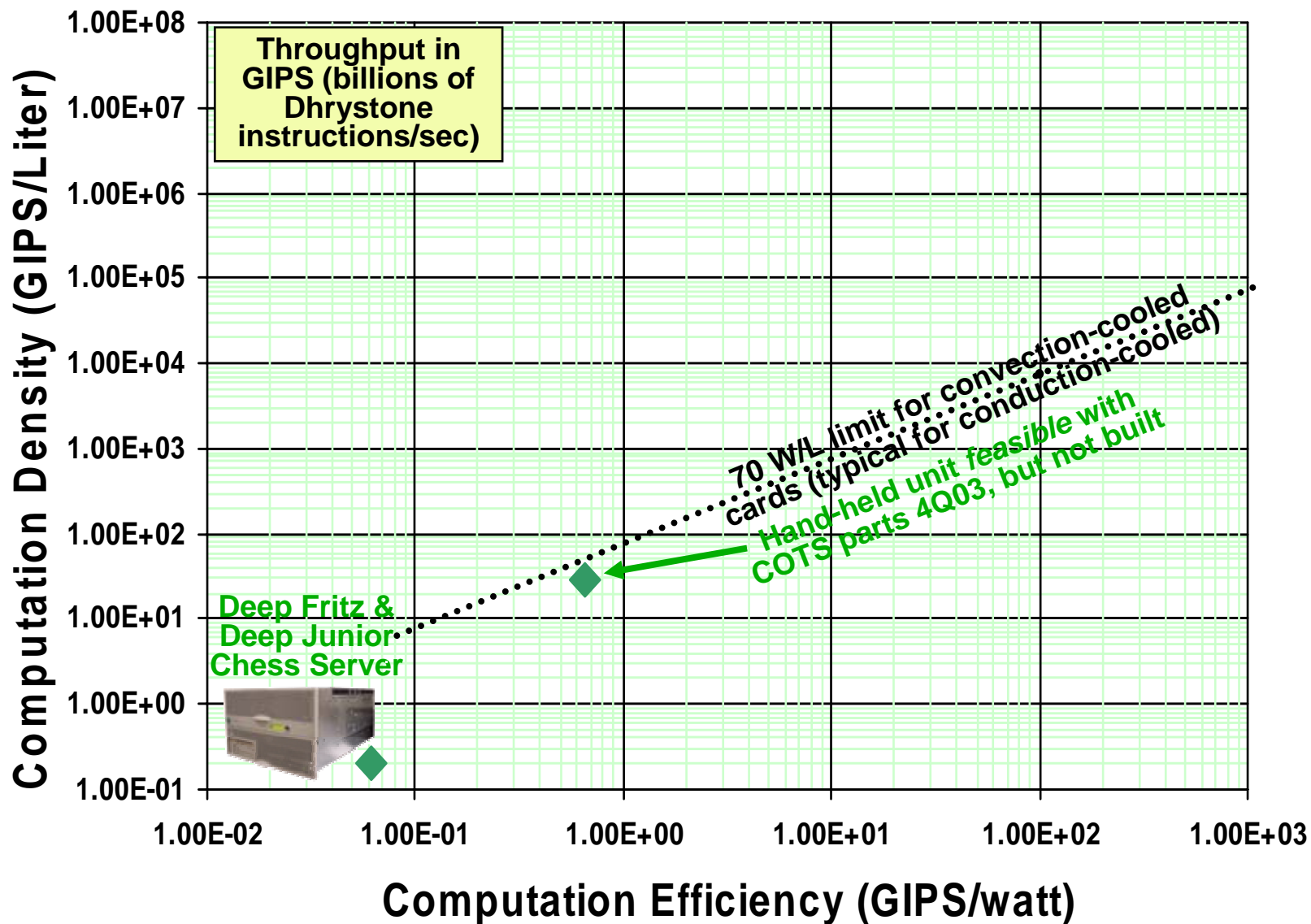
~2008



Deep Yogurt has 1/3 the size & power of Deep Dew, with **3X improvement in 3 yrs**

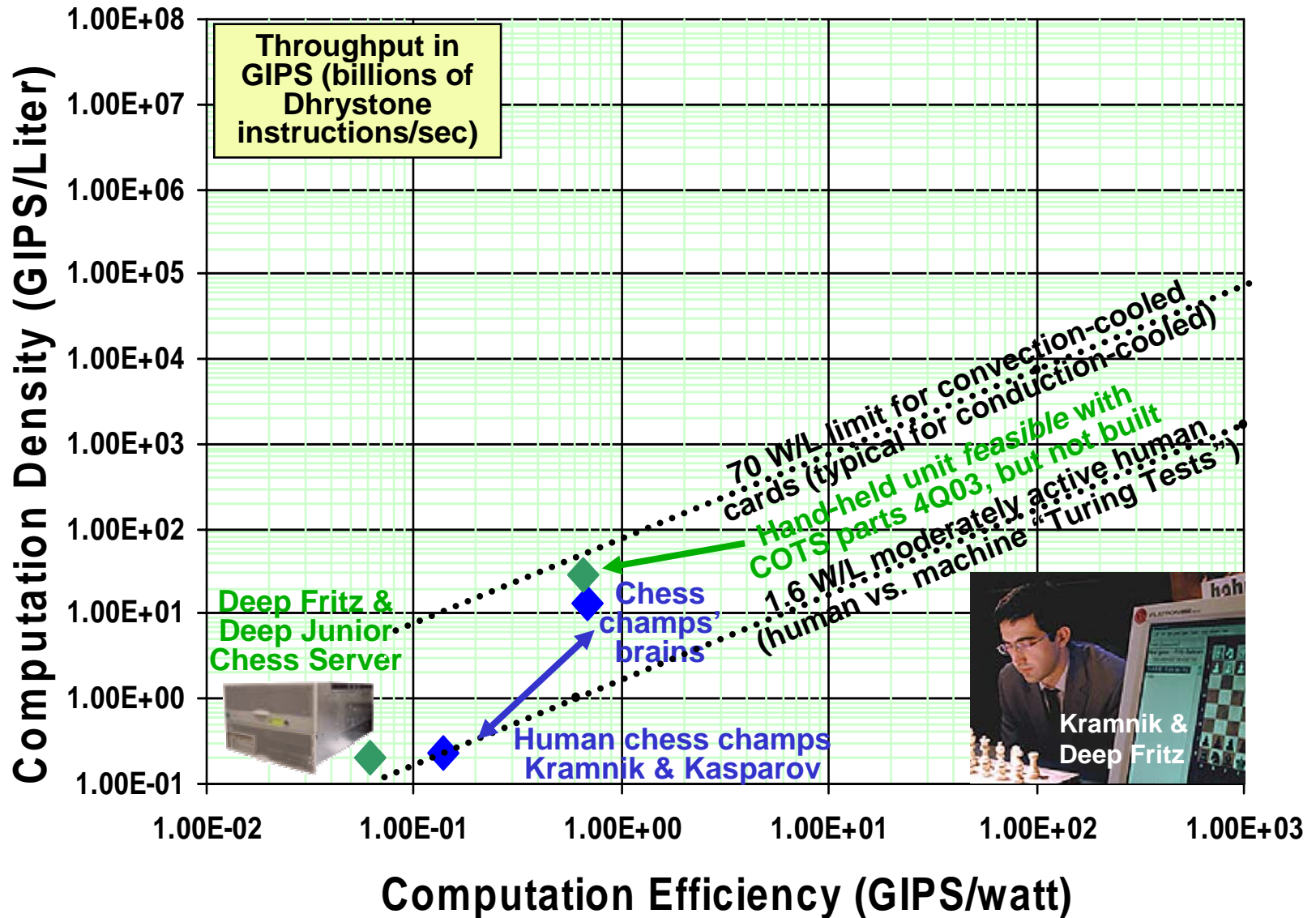


# Power per Unit Volume (Watts/Liter) for Representative Systems ca. 2003



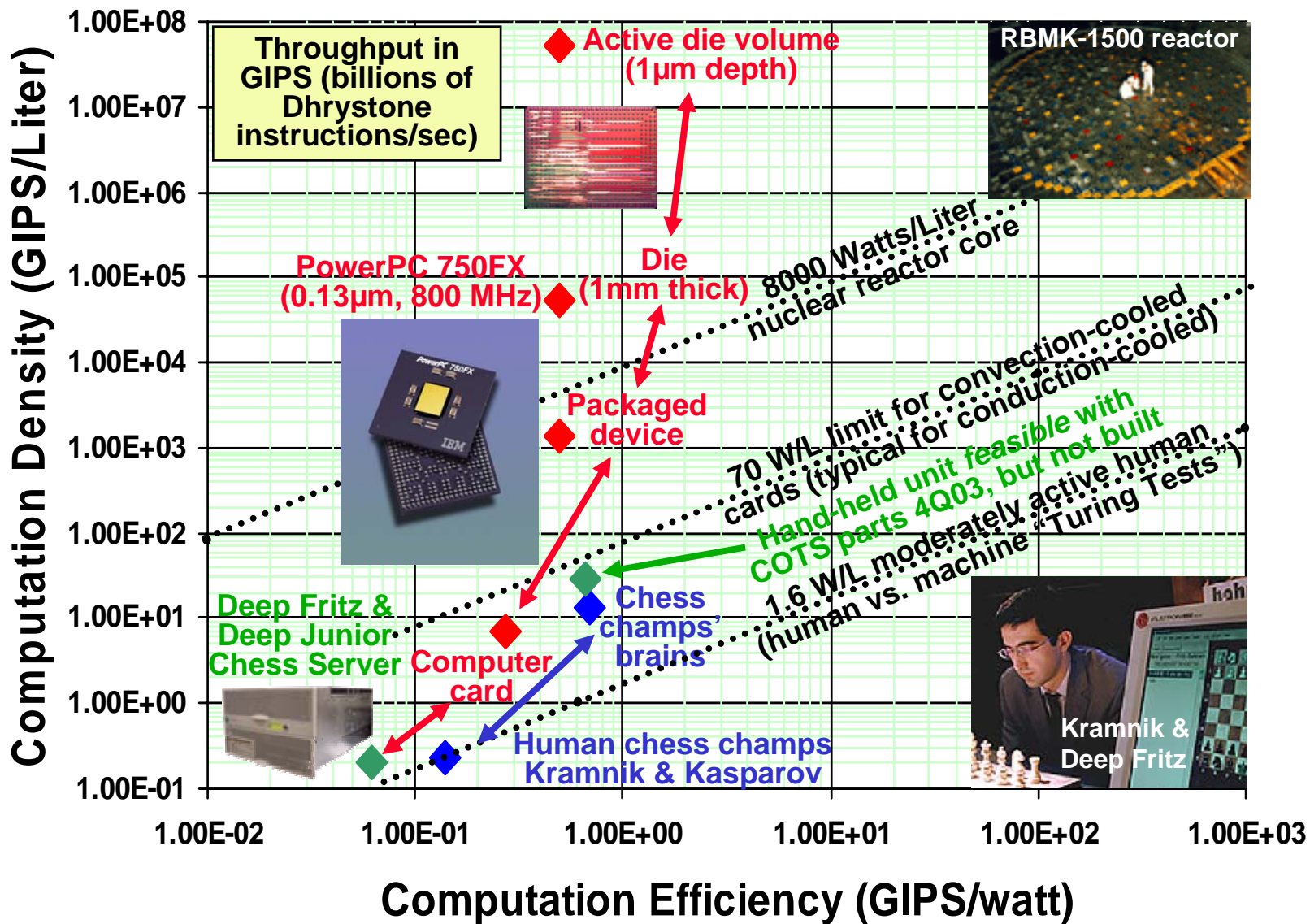


# Power per Unit Volume (Watts/Liter) for Representative Systems ca. 2003



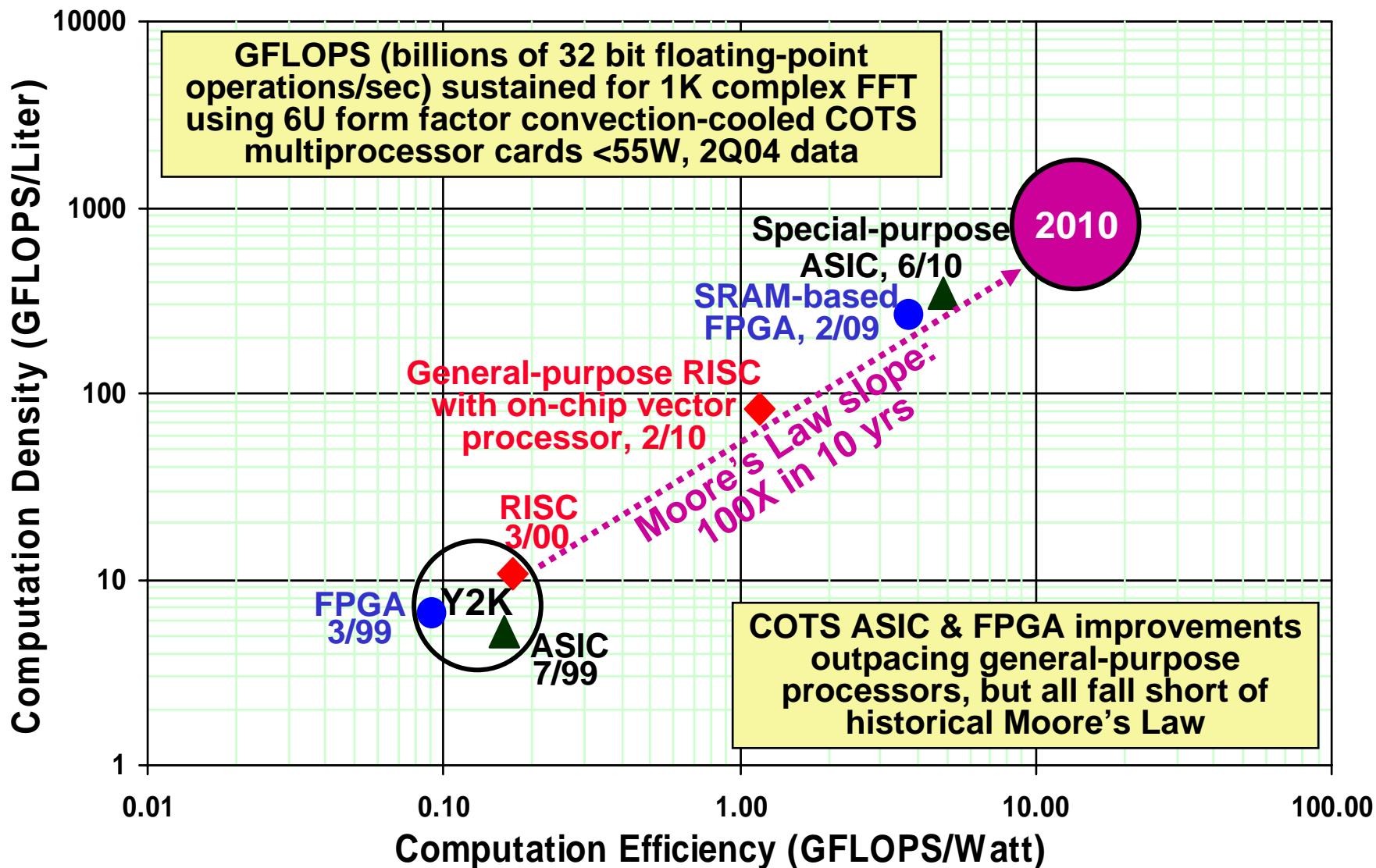


# Power per Unit Volume (Watts/Liter) for Representative Systems ca. 2003



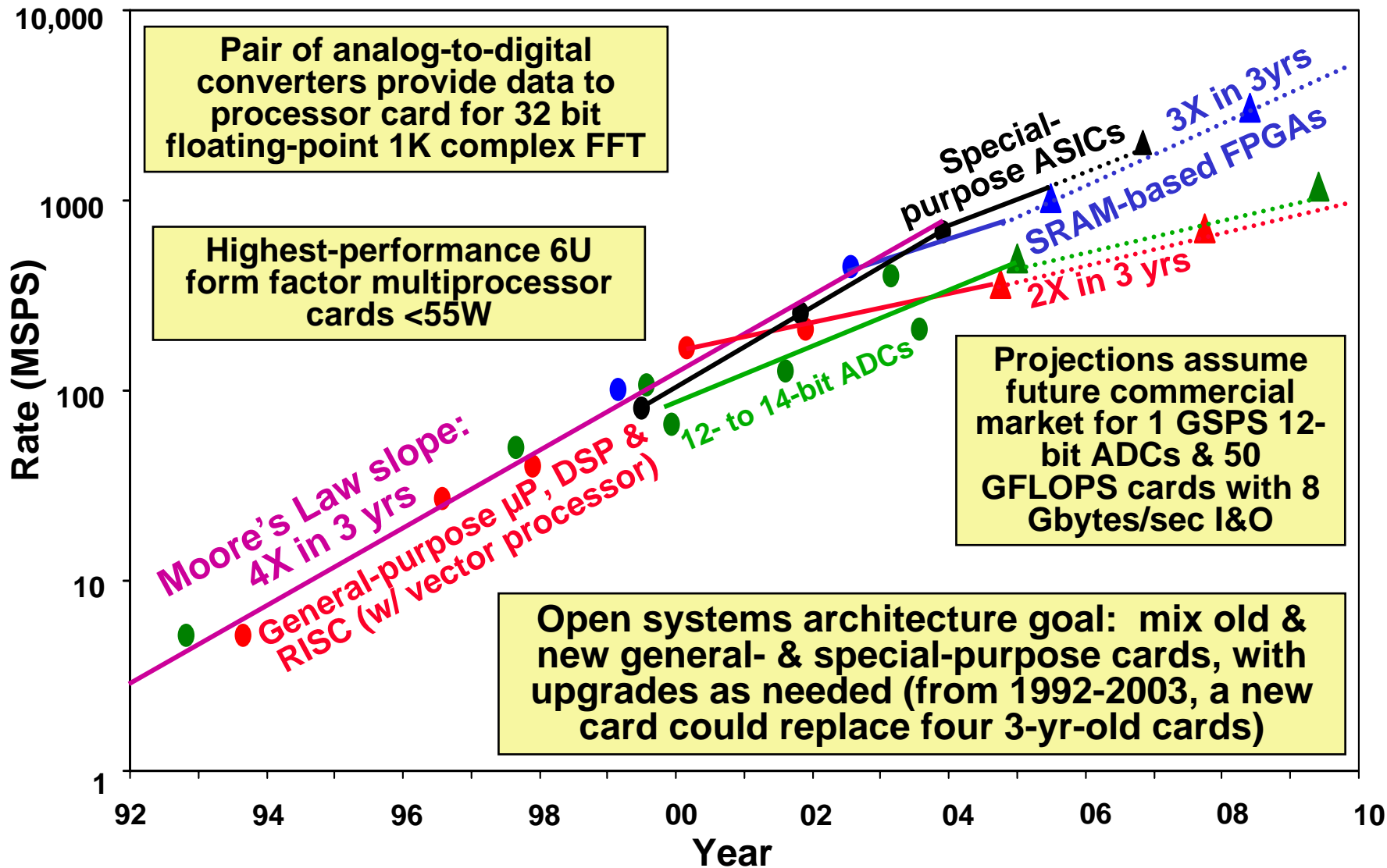


# System-level Improvements Falling Short of Historical Moore's Law





# Timeline for ADC Sampling Rate & COTS Processors (2Q04)





# Representative Embedded Computing Applications



**Radio** for soldier's software-defined comm/nav system (**severe size, weight & power constraints**)

**Sonar** for anti-submarine rocket-launched lightweight torpedo (**high throughput requirements** but low data rates)



**Radar** for mini-UAV surveillance applications (**stressing I/O data rates**)

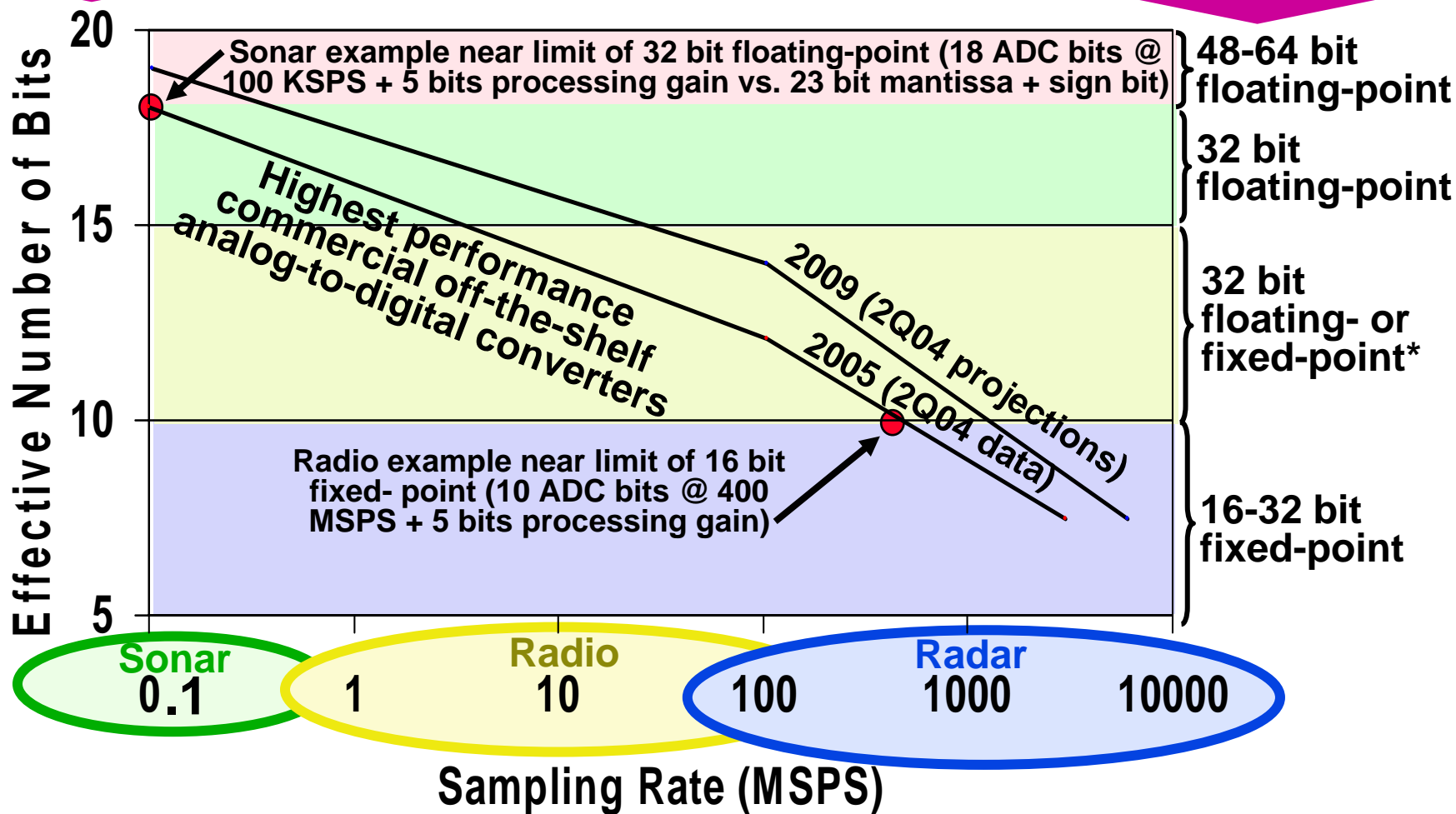
**Cost- & schedule-sensitive real-time applications with high RAS (reliability, availability & serviceability) requirements**



# Embedded Signal Processor Speed & Numeric Representations Must Track ADC Improvements

ADC ENOB

Typical Processor Numeric Representation



\*Floating-point preferred (same memory & I/O as fixed-point)





# Objective, Questions for the Panel & Schedule

- **Objective: identify & characterize factors that affect the impact of Moore's Law on embedded applications**
- **Questions for the panel**
  - 1). Moore's Law: what's causing the slowdown?
  - 2). What is the contribution of Moore's Law to improvements at the embedded system level?
  - 3). Can we preserve historical improvement rates for embedded applications?

**Panel members & audience may hold diverse, evolving opinions**

- **Schedule**
  - 1540-1600: panel introduction & overview
  - – 1600-1620: guest speaker Dr. Robert Schaller
  - 1620-1650: panelist presentations
  - 1650-1720: open forum
  - 1720-1730: conclusions & the way ahead



# Objective, Questions for the Panel & Schedule

- **Objective: identify & characterize factors that affect the impact of Moore's Law on embedded applications**
- **Questions for the panel**
  - 1). Moore's Law: what's causing the slowdown?
  - 2). What is the contribution of Moore's Law to improvements at the embedded system level?
  - 3). Can we preserve historical improvement rates for embedded applications?

**Panel members & audience may hold diverse, evolving opinions**

- **Schedule**
  - 1540-1600: panel introduction & overview
  - 1600-1620: guest speaker Dr. Robert Schaller
  - 1620-1650: panelist presentations
  - – 1650-1720: open forum
  - 1720-1730: conclusions & the way ahead



# Conclusions & The Way Ahead

- **Slowdown in Moore's Law due to a variety of factors**
  - Improvement rate was 4X in 3 yrs, now 2-3X in 3 yrs (still substantial)
  - Impact of slowdown greatest in “leading edge” embedded applications
  - Software issues may overshadow Moore's Law slowdown
- **COTS markets may not emerge in time to support historical levels of improvement**
  - Federal government support may be required in certain areas (e.g., ADCs)
  - Possible return of emphasis on advanced packaging and custom devices/technologies for military embedded applications
- **Developers need to overcome issues with I/O standards & provide customers with cost-effective solutions in a timely manner: success may depend more on economic & political rather than technical considerations**
- **Hardware *can* be designed to drive down software cost/schedule, but new methodologies face barriers to acceptance**
- **Improvements clearly come both from Moore's Law & algorithms, but better metrics needed to measure relative contributions**

**“It's absolutely critical for the federal government to fund basic research. Moore's Law will take care of itself. But what happens after that is what I'm worried about.”  
- Gordon Moore, Nov. 2001**



# Backup Slides

---

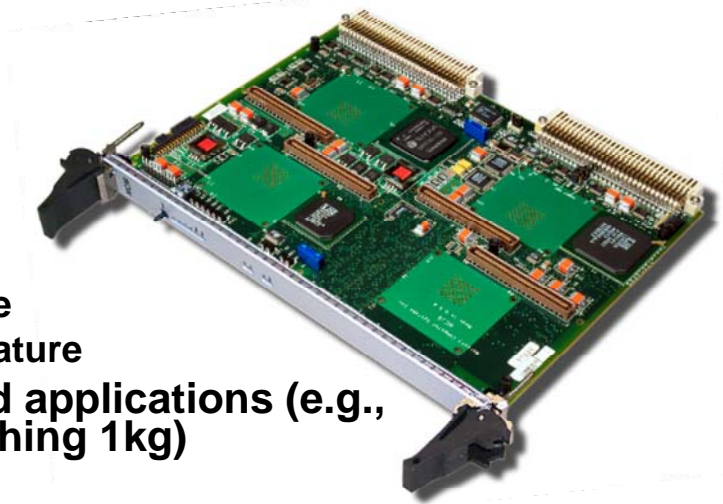


# Points of Reference

- **6U form factor card**

- Historical data available for many systems
- Convection cooled
  - Fans blow air across heat sinks
  - Rugged version uses conduction cooling
- Size: 16x23cm, 2cm slot-to-slot (0.76L)
- Weight: 0.6kg, typ.
- Power: 54W max. (71W/L)
  - Power limitations on connectors & backplane
  - Reliability decreases with increasing temperature
- Can re-package with batteries for hand-held applications (e.g., walkie-talkie similar to 1L water bottle weighing 1kg)

COTS (commercial off-the-shelf) 6U multiprocessor card



- **1024-point complex FFT (fast Fourier transform)**

- Historical data available for many computers (e.g., fftw.org)
- Realistic benchmark that exercises connections between processor, memory and system I/O
- Up to 5 bits processing gain for extracting signals from noise
- Expect 1 $\mu$ sec/FFT (32 bit floating-point) on 6U COTS card ~7/05
  - Assume each FFT computation requires 51,200 real operations
  - 51.2 GFLOPS (billions of floating point operations/sec) throughput
  - 1024 MSPS (million samples/sec, complex) sustained, simultaneous input & output (8 Gbytes/sec I&O)



# Moore's Law & Variations, 1965-1997

- “Original” Moore’s Law (1965, revised 1975)
  - **4X transistors/die every 3 yrs**
  - Held from late '70s - late '90s for DRAM (dynamic random access memory), the most common form of memory used in personal computers
  - Improvements from decreasing geometry, “circuit cleverness,” & increasing die size
  - Rates of speed increase & power consumption decrease not quantified
- “Amended” Moore’s Law: 1997 National Technology Roadmap for Semiconductors (NTRS97)
  - Models provided projections for 1997-2012
  - Improvement rates of 1.4X speed @ constant power & 2.8X density (transistors per unit area) every 3 yrs
  - For constant power, speed x density gave **max 4X performance improvement every 3 yrs**
  - **Incorrectly predicted 560 mm<sup>2</sup> DRAM die size for 2003 (4X actual)**

Historically,  
Performance =  $2^{\text{Years}/1.5}$



# Moore's Law Slowdown, 1999-2003 (recent experience with synchronous DRAM)

- Availability issues: **production did not come until 4 yrs after development** for 1Gbit DDR (double data rate) SDRAMs (7/99 – 7/03)
- SDRAM price crash
  - **73X reduction in 2.7 yrs** (11/99 – 6/02)
  - Justice Dept. price-fixing investigation began in 2002
- Reduced demand
  - Users unable to take advantage of improvements as **\$3 SDRAM chip holds 1M lines of code having \$100M development cost** (6/02)
  - Software issues made Moore's Law seem irrelevant
    - Moore's Law impacted HW, not SW
    - Old SW development methods unable to keep pace with HW improvements
    - SW slowed at a rate faster than HW accelerated
    - Fewer projects had HW on critical path
    - In 2000, 25% of U.S. commercial SW projects (\$67B) canceled outright with no final product**
    - 4 yr NASA SW project canceled (9/02) after 6 yrs (& \$273M) for being 5 yrs behind schedule**

**System-level improvement rates possibly slowed by factors not considered in Moore's Law "roadmap" models**



# The End of Moore's Law, 2004-20XX

- **2003 International Technology Roadmap for Semiconductors (ITRS03)**
  - Models provide projections for 2003-2018
  - 2003 DRAM size listed as 139 mm<sup>2</sup> (1/4 the area predicted by NTRS97)
  - Predicts that future DRAM die will be *smaller* than in 2003
  - Improvement rates of 1.5X speed @ constant power & 2X density every 3 yrs
  - Speed x density gives **max 3X performance improvement every 3 yrs**
  - Limited by lithography improvement rate (partially driven by economics)
- **Future implications (DRAMs & other devices)**
  - Diminished “circuit cleverness” for mature designs (chip & card level)
  - Die sizes have stopped increasing (and in some cases are decreasing)
  - Geometry & power still decreasing, but at a reduced rate
  - Fundamental limits (e.g., speed of light) may be many (more) years away
    - Nearest-neighbor architectures
    - 3D structures
  - Heat dissipation issues becoming more expensive to address
  - More chip reliability & testability issues
  - Influence of foundry costs on architectures may lead to fewer device types in latest technology (e.g., only SDRAMs and static RAM-based FPGAs)

**Slower (*but still substantial*) improvement rate predicted, with greatest impact on systems having highest throughput & memory requirements**





# High-Performance MPU (microprocessor unit) & ASIC (application-specific integrated circuit) Trends

Year of production	2004	2007	2010	2013	2016
MPU/ASIC 1/2 pitch, nm	90	65	45	32	22
Transistors/chip	553M	1106M	2212M	4424M	8848M
Max watts @ volts	158@1.2	189@1.1	218@1.0	251@0.9	288@0.8V
Clock freq, MHz	4,171	9,285	15,079	22,980	39,683
Clock freq, MHz, for 158W power	4,171	7,762	10,929	14,465	21,771

- **2003 International Technology Roadmap for Semiconductors**
  - <http://public.itrs.net>
  - Executive summary tables 1i&j, 4c&d, 6a&b
  - Constant 310 mm<sup>2</sup> die size
- **Lithography improvement rate (partially driven by economics) allows 2X transistors/chip every 3 yrs**
  - 1.5X speed @ constant power
  - ~3X throughput for multiple independent ASIC (or FPGA) cores while maintaining constant power dissipation
  - ~2X throughput for large-cache MPUs (constant throughput/memory), but power may possibly decrease with careful design



# Bottleneck Issues

- **Bottlenecks occur when interconnection bandwidth (e.g., processor-to-memory, bisection or system-level I/O) is inadequate to support the throughput for a given application**
- **For embedded applications, I/O bottlenecks are a greater concern for general-purpose, highly interconnected back-end vs. special-purpose, channelized front-end processors**

**Can developers provide timely, cost-effective solutions to bottleneck problems?**



# Processor Bottlenecks at Device & System Levels

- **Device level (ITRS03)**

- **2X transistors & 1.5X speed every 3 yrs**  
High-performance microprocessor units & ASICs  
Constant power & 310 mm<sup>2</sup> die size
- **3X throughput every 3 yrs *possible* if chip is mostly logic gates changing state frequently (independent ASIC or FPGA cores)**
- **2X throughput every 3 yrs is limit for microprocessors with large on-chip cache (chip is mostly SRAM & throughput/memory remains constant)**
- **Possible technical solutions for microprocessors: 3D structures, on-chip controller for external L3 cache**

- **System level**

- **54W budget for hypothetical 6U COTS card computing 32 bit floating-point 1K complex FFT every 1μsec**  
10% (5W) DC-to-DC converter loss  
40% (22W) I/O (7 input & 7 output links @ 10 Gbits/sec & 1.5W ea., RF coax, 2004)  
50% (27W) processor (51 GFLOPS sustained) & memory (5 Gbytes)
- **Possible technical solutions for I/O**  
RF coax point-to-point serial links with central crosspoint switch network (PIN diodes or MEMS switches)  
Fiber optic links (may require optical free-space crosspoint switch) & optical chip-to-chip interconnects



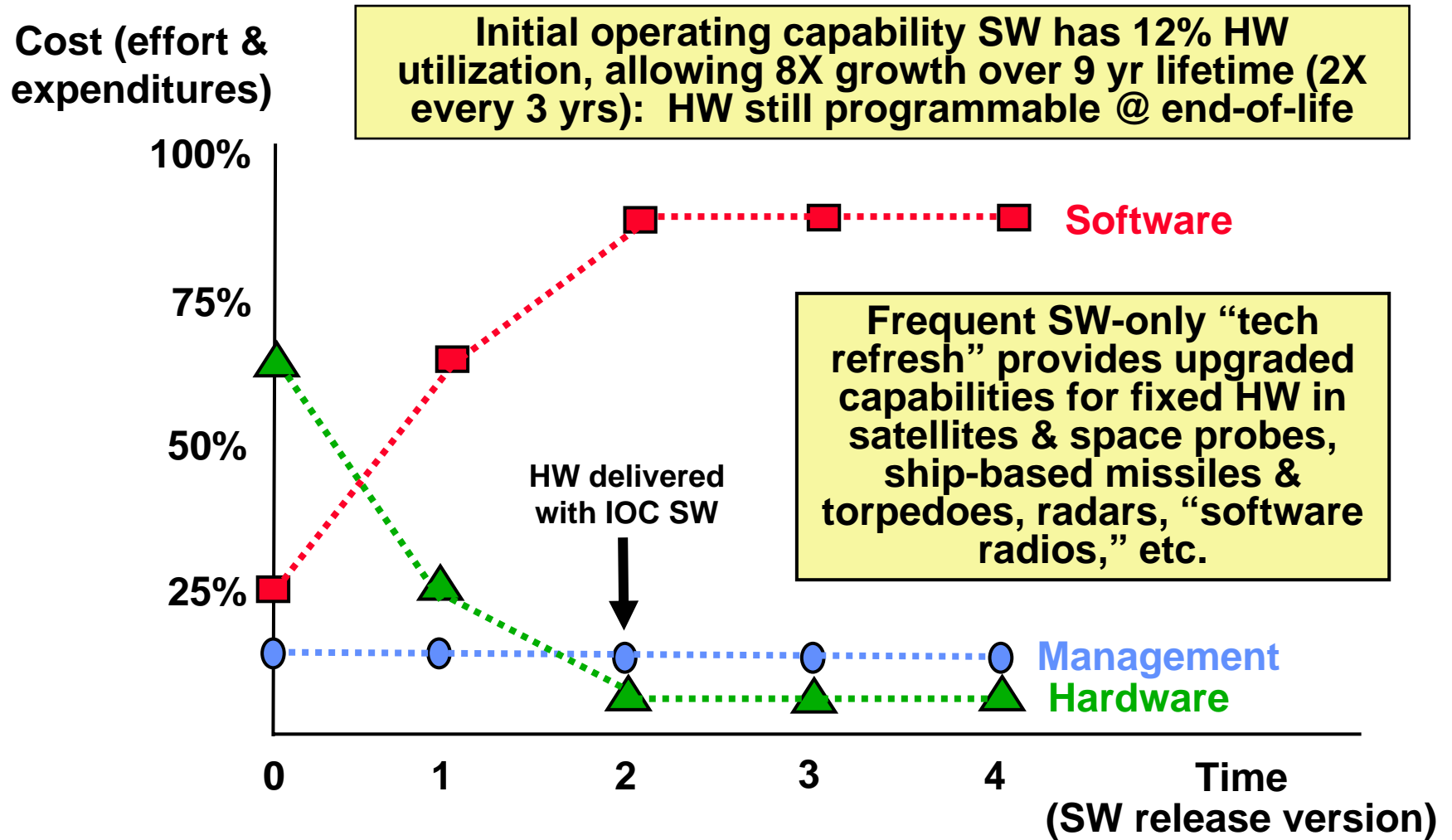
# Examples of Hardware vs. Algorithms

- **Static RAM-based FPGAs**
  - 2002: system-level throughput improved substantially vs. 1999
  - 2/3 of improvement attributable to new devices, 1/3 to architecture changes
- **Chess computers**
  - 1997: Deep Blue provided 40 trillion operations per second using 600nm custom ASICs (but 250nm was state-of-the-art)
  - 2001: Desktop version of Deep Blue using state-of-the-art custom ASICs feasible, but not built
  - 2002-2003: improved algorithms provide functional equivalent of Deep Blue using COTS servers instead of custom ASICs
- **Speedup provided by FFT & other “fast” algorithms**

**Contributions of HW vs. algorithms may be difficult to quantify, even when all necessary data are available**

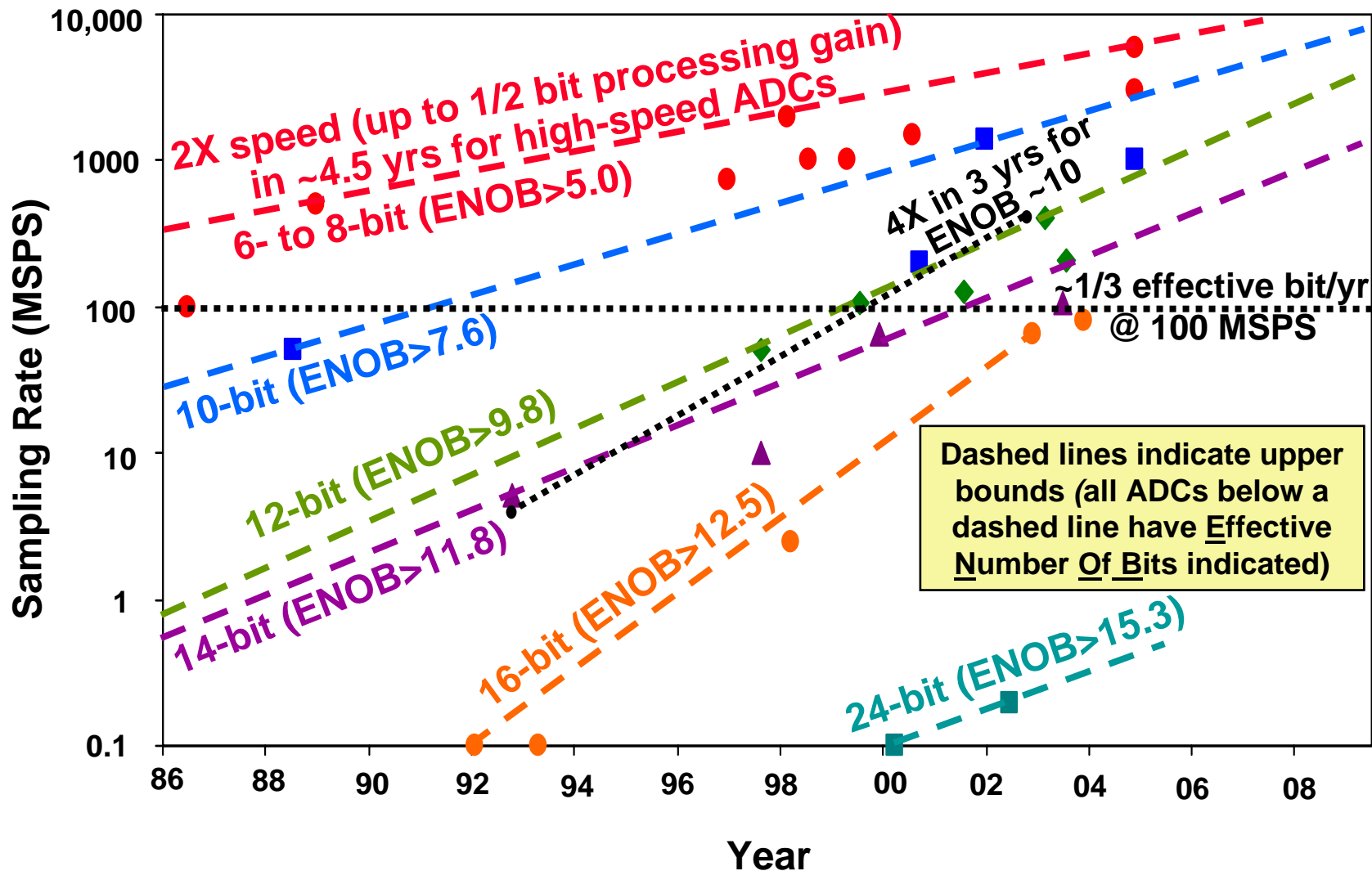


# Cost vs. Time for Modern HS/SW Development Process (normalized to a constant funding level)



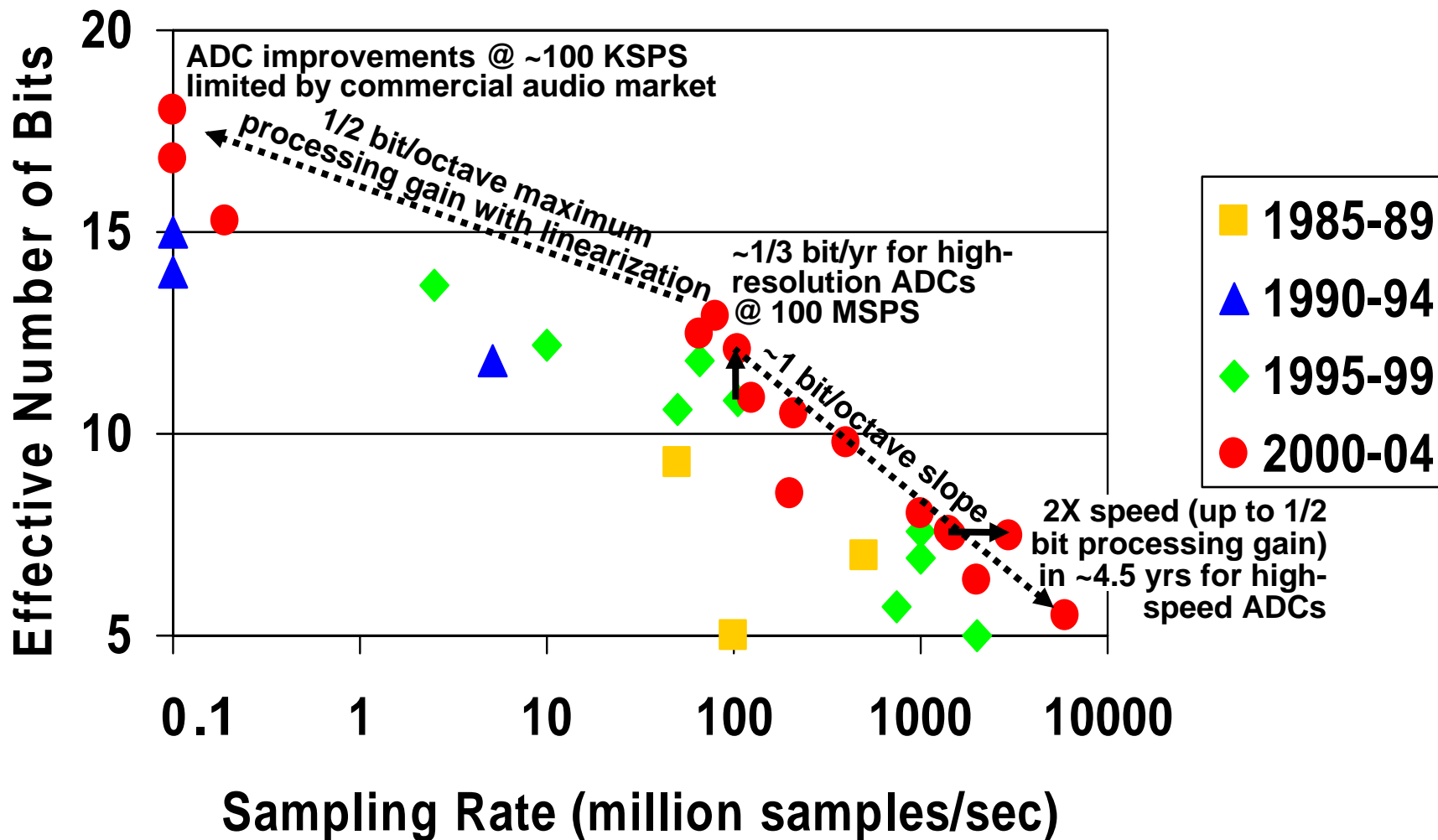


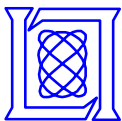
# Timeline for Highest Performance COTS ADCs, 2Q04



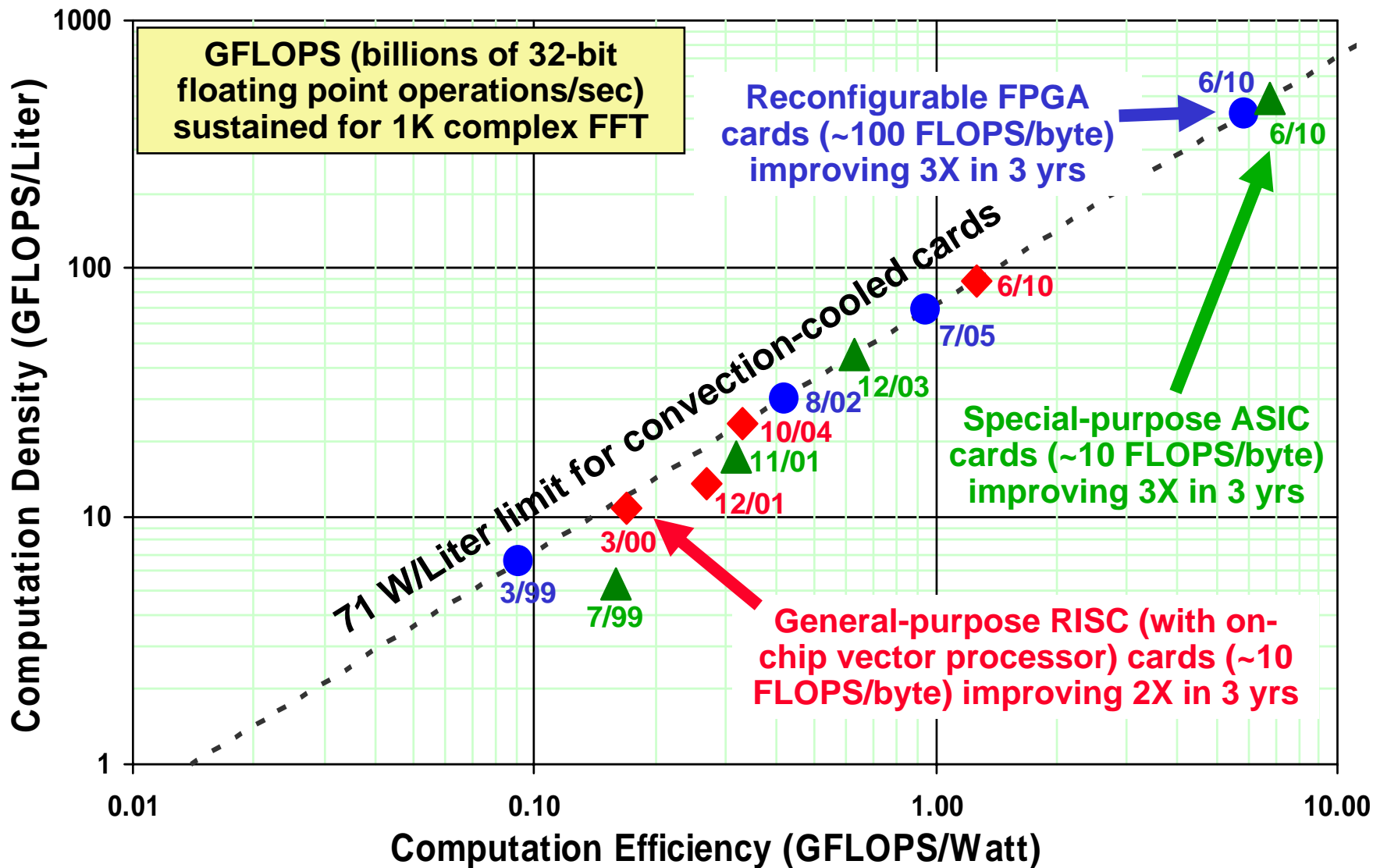


# Improvement Rates for Highest Performance COTS ADCs, 2Q04





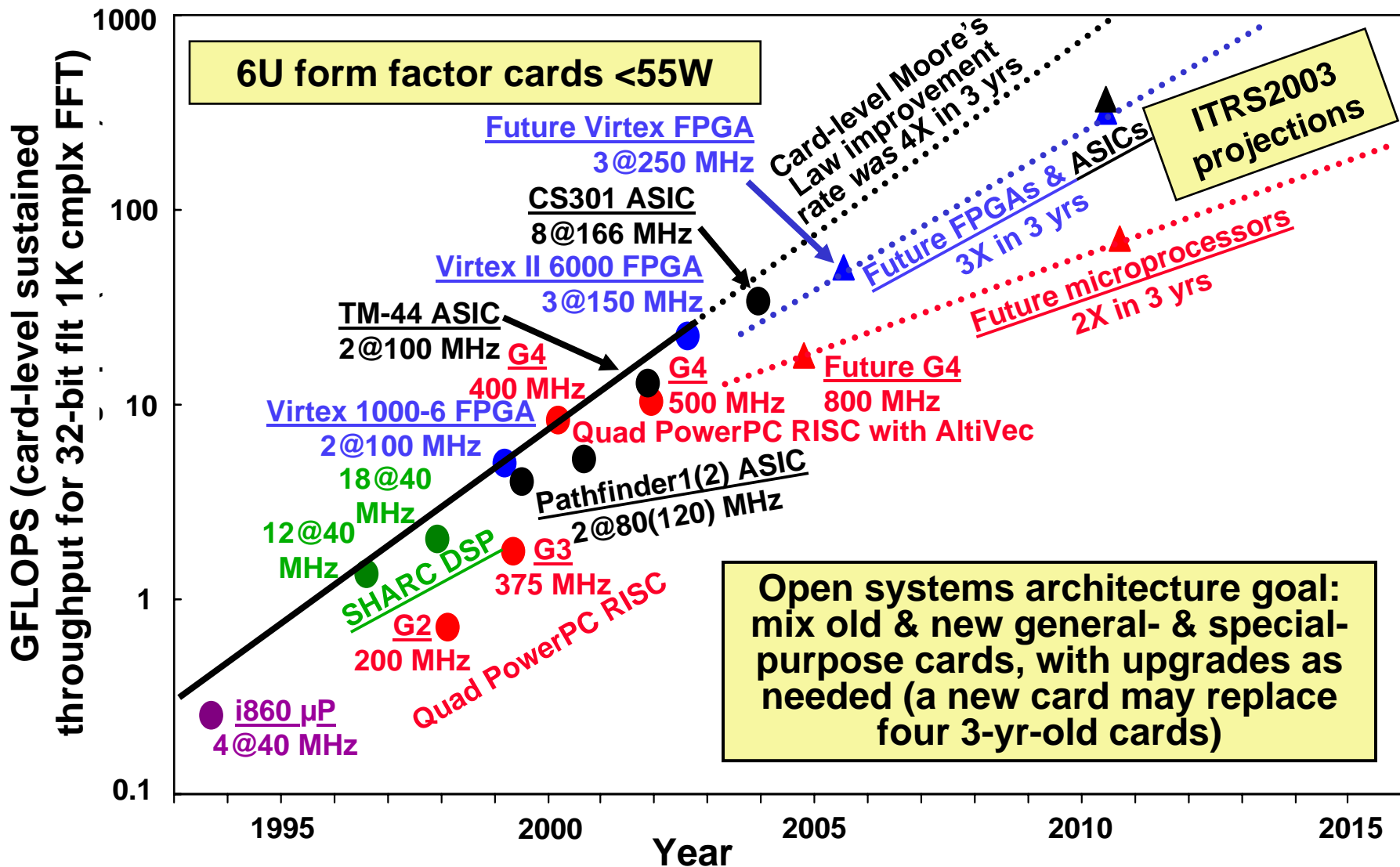
# Evolution of COTS Embedded Multiprocessor Cards, 2Q04

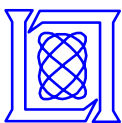






# Timeline for Highest Performance COTS Multiprocessors, 2Q04





# Timeline for COTS Processor I&O Rate and ADC Sampling Rate (2Q04)

